

REMARKS

The foregoing amendments and the following remarks are responsive to the Office Action mailed June 30, 2003. Applicants respectfully request reconsideration of the present application.

Claims 13-19 are pending. Claims 13, 14, 16, 18 and 19 are amended. Claims 20-40 are withdrawn. Please cancel withdrawn claims 20-40. New claims 41-53 have been added. Therefore, claims 13-19 and 41-53 are presented for examination.

Claims 14, 16 and 18-19 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Examiner rejected claim 13 under 35 U.S.C. §102(b) as being unpatentable over U.S. Patent No. 4,152,679 issued to Chen. Examiner rejected claims 13 and 14 under 35 U.S.C. §102(b) as being unpatentable over U.S. Patent No. 4,416,056 issued to Takahashi. Examiner rejected claims 15 and 16 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 4,152,679 issued to Chen in view of U.S. Patent No. 5,208,656 issued to Matsuyama, et al. Examiner rejected claim 17 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 4,152,679 issued to Chen in view of U.S. Patent No. 5,393,697 issued to Chang, et al. Examiner rejected claim 18 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 4,416,056 issued to Takahashi in view of U.S. Patent No. 5,208,656 issued to Matsuyama, et al. Examiner rejected claim 19 under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 4,152,679 issued to Chen in view of U.S. Patent No. 5,208,656 issued to Matsuyama, et al., and further in view of U.S. Patent No. 5,393,697 issued to Chang, et al.

Chen discusses micro-miniature thin film inductance coils, using interconnections of permalloy. The inductance coils of Chen included a plurality of superimposed coaxial turns 20 of electrically conductive metal film with adjacent turns isolated electrically from each other by interposed film 22 of dielectric material. (Chen,

column 2, lines 38-42). Chen provides terminals 24, 26 by extending the innermost and outermost turns laterally. (Chen, column 2, lines 42-44). The Examiner suggests that element 22, the dielectric material of Chen, is a post. However, Applicants respectfully submit that the dielectric material is used simply to isolate adjacent turns of a micro-miniature coils of Chen's inductor. Figure 3 of Chen shows a cross-cut of the circuit.

Chen does not teach or suggest posts over the insulating layer and a conductive layer deposited on top of the posts and in a pattern on the substrate, the conductive layer on the tops of the posts for coupling the packaged inductor to another device. Therefore, claim 13, as amended, is not anticipated by Chen.

Takahashi discusses a process for preparing film coils to produce an inductor, transformer, and similar devices. Takahashi discusses multiple layers of semi-conductors formed (layers 25, 16, 28) insulated from each other by insulating layers (layers 26, 13, 17, 37). The connection for Takahashi's inductor is through "the outer end portions 11A and 40 of the first and fourth layer conductor patterns 11 and 40 are used as terminals for connection of outside wires. (Takahashi, column 5, lines 38-40). The Examiner suggests that layer 16 of Takahashi is a post. Applicants respectfully submit that layer 16 is the "second layer conductor pattern (Takahashi, column 5, lines 3-4), and does not in any way correspond to a post.

Therefore, Takahashi does not teach or suggest posts over the insulating layer and a conductive layer deposited on top of the posts and in a pattern on the substrate, the conductive layer on the tops of the posts for coupling the packaged inductor to another device. Therefore, claim 13, as amended, is not anticipated by Takahashi.

Matsuyama discusses a multi-layer wiring substrate. Matsuyama does not teach or suggest producing a packaged device, having posts, in which the conductive layers on tops of the posts are for coupling the packaged device to another device.

Chang discusses composite bumps which serve as the physical and electrical connection between the integrated circuit element and the next level of integration.

(Chang, Field of the Invention). Chang does not teach or suggest producing a packaged device having posts, in which the conductive layers on tops of the posts are for coupling the packaged device to another device.

Therefore, claims 13-19, and new claims 41-55 are not obvious over the combination of Chen, Takahashi, Matsuyama, and Chang.


In view of the foregoing amendments and remarks, applicants respectfully submit that all pending claims are in condition for allowance. Such allowance is respectfully requested.

If the Examiner finds any remaining impediment to the prompt allowance of these claims that could be clarified with a telephone conference, the Examiner is respectfully requested to contact Judith A. Szepesi at (408) 720-8598.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

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